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**REMARKS**

In response to the above-identified Final Office Action, Applicants amend the application and seek reconsideration thereof. In this reply, Applicants amend claims 1, 9, 14, and 22, and add new claim 28. Applicants do not cancel any claims. Applicants submit no new matter is added by these amendments. Accordingly, claims 1-28 are pending.

**Claim Rejections - 35 U.S.C. §102**

Claims 1-27 stand rejected under 35 U.S.C. 102(e) as being anticipated by U.S. Patent No. 5,554,940 issued to Hubachaer ("Hubachaer"). Applicants traverse the rejection but amend claims 1, 9, 14, and 22 to expedite prosecution.

To anticipate a claim, the cited reference must teach every element of the rejected claim. Among other elements, claim 1, as amended, defines a method for forming a die comprising "forming a conductive path between said at least one input bond pad and said at least one test pad, wherein a portion of said conductive path is formed on said die between an edge of said die and said active portion of said die." Applicants submit Hubachaer fails to teach at least these elements of claim 1

In making the rejection, the Examiner characterizes Hubachaer as disclosing each of the elements of claim 1, and particularly, "wherein a portion of the conductive path is formed on the die outside of the active portion of the die" (Paper No. 030204, pages 2-3). Applicants disagree with the Examiner's characterization of Hubachaer since Hubachaer states "It should be noted that as illustrated in FIG. 3 [and subsequent FIGs], die 10 is incomplete in that active devices [i.e., active portions] and the semiconducting substrate of the die are not illustrated; however, these aspects of die 10 are not important to understanding the present

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invention, and furthermore are well understood within the art." Hubachaer, Col. 4, line 65 – Col. 5, line 4. As such, Hubachaer does not specifically teach "a portion of the conductive path is formed on the die outside of the active portion of the die" since Hubachaer states that the FIGs and the text does not include reference and illustration of the active and inactive portions of die 10. However, to expedite prosecution, Applicants amend claim 1 to clarify claim 1.

Applicants submit Hubachaer teaches a die wherein a test pad interconnect (reference number 36) connects a via pad (reference number 34) and a test pad (reference number 28) in an area not between an edge of die 10 and an active portion of die 10 (i.e., bond pad 12). See Hubachaer, FIG. 6, FIG. 8, FIG. 10, and FIG. 14. As such, Hubachaer fails to teach each of the elements of claim 1.

The failure of Hubachaer to teach each of the elements of claim 1 is fatal to the anticipation rejection. Therefore, claim 1 cannot be anticipated by Hubachaer. Accordingly, Applicants respectfully request withdrawal of the rejection of claim 1.

Claims 2-8 each either directly or indirectly depend from claim 1 and contain all of the elements thereof. Therefore, Applicants submit claims 2-8 are not anticipated by Hubachaer at least for the same reasons as claim 1, in addition to their own respective features. Accordingly, Applicants respectfully request withdrawal of the rejection of claims 2-8.

Applicants submit independent claim 9, 14, and 22 each include the elements of "forming a conductive path between said at least one input bond pad and said at least one test pad, wherein a portion of said conductive path is formed on said die between an edge of said die and said active portion of said die" similar to claim 1. Therefore, Applicants submit

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claims 9, 14, and 22 are not anticipated by Hubachaer at least for the same reasons as claim 1, in addition to their own respective features. Accordingly, Applicants respectfully request withdrawal of the rejection of independent claims 9, 14, and 22.

Claims 10-13, 15-21, and 23-27 each either directly or indirectly depend from claims 9, 14, and 22, respectively, and contain all of the elements thereof. Therefore, Applicants submit claims 10-13, 15-21, and 23-27 are not anticipated by Hubachaer at least for the same reasons as claims 9, 14, and 22, in addition to their own respective features. Accordingly, Applicants respectfully request withdrawal of the rejection of claims 10-13, 15-21, and 23-27.

New Claim

Applicants have added claim 28. Applicants submit claim 28 is not anticipated by Hubachaer since Hubachaer fails to teach at least "a portion of said each of said conductive lines is formed on a scribe area outside the die" as recited in claim 28. Accordingly, Applicants submit claim 28 is in condition for allowance.

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**Conclusion**

In view of the foregoing, it is believed that all claims now pending are in condition for allowance. A Notice of Allowance if earnestly solicited at the earliest possible date. If the Examiner believes that a telephone conference would be useful in moving the application forward to allowance, the Examiner is encouraged to contact the undersigned.

If necessary, the Commissioner is hereby authorized to charge payment or credit any overpayment to Deposit Account No. 1928-14 for any additional fees required under 37 C.F.R. §§ 1.16 or 1.17, particularly extension of time fees.

Respectfully submitted,

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